

# Yi Cui

## List of Publications by Year in Descending Order

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The third column is the impact factor (IF) of the journal, and the fourth column is the number of citations of the article.

17  
papers

131  
citations

7  
h-index

11  
g-index

17  
ext. papers

160  
ext. citations

3.1  
avg, IF

3.55  
L-index

#	Paper	IF	Citations
17	Nanotwinning and tensile behavior in cold-welded high-entropy-alloy nanowires. <i>Nanotechnology</i> , <b>2021</b> , 32,	3.4	3
16	Evaluation of Electric Current-Induced Improvement of Fracture Characteristics in SUS316. <i>Materials Transactions</i> , <b>2021</b> , 62, 748-755	1.3	
15	The deformation mechanism in cold-welded gold nanowires due to dislocation emission. <i>Computational Materials Science</i> , <b>2021</b> , 188, 110214	3.2	4
14	Relief of strain hardening in deformed Inconel 718 by high-density pulsed electric current. <i>Journal of Materials Science</i> , <b>2021</b> , 56, 16686-16696	4.3	3
13	High-strain-rate void growth in high entropy alloys: Suppressed dislocation emission = suppressed void growth. <i>Scripta Materialia</i> , <b>2020</b> , 185, 12-18	5.6	9
12	True origin of the size effect in cold-welded metallic nanocrystals. <i>International Journal of Mechanical Sciences</i> , <b>2020</b> , 187, 106102	5.5	4
11	Fracture of void-embedded high-entropy-alloy films: A comprehensive atomistic study. <i>Materialia</i> , <b>2020</b> , 12, 100790	3.2	4
10	Mass transfer and morphology change via dislocation emission in a macroporous FCC metal. <i>Materials Letters</i> , <b>2019</b> , 247, 67-70	3.3	11
9	Atomistic treatment of periodic gold nanowire array nanofasteners under shear loading. <i>Nanotechnology</i> , <b>2019</b> , 31, 105704	3.4	4
8	Fundamental insights into the mass transfer via full dislocation loops due to alternative surface cuts. <i>International Journal of Solids and Structures</i> , <b>2019</b> , 161, 42-54	3.1	11
7	New mechanisms of helical dislocation formation via the pinch-off process near a nano-inhomogeneity. <i>Computational Materials Science</i> , <b>2018</b> , 155, 400-409	3.2	5
6	Void initiation from interfacial debonding of spherical silicon particles inside a silicon-copper nanocomposite: a molecular dynamics study. <i>Modelling and Simulation in Materials Science and Engineering</i> , <b>2017</b> , 25, 025007	2	9
5	Simulation of mechanical performance of nanoporous FCC copper under compression with pores mimicking several crystalline arrays. <i>Journal of Applied Physics</i> , <b>2017</b> , 122, 075102	2.5	4
4	Material transport via the emission of shear loops during void growth: A molecular dynamics study. <i>Journal of Applied Physics</i> , <b>2016</b> , 119, 225102	2.5	19
3	Molecular dynamics simulation of the influence of elliptical void interaction on the tensile behavior of aluminum. <i>Computational Materials Science</i> , <b>2015</b> , 108, 103-113	3.2	28
2	Molecular dynamics modeling on the role of initial void geometry in a thin aluminum film under uniaxial tension. <i>Modelling and Simulation in Materials Science and Engineering</i> , <b>2015</b> , 23, 085011	2	13
1	Investigating size dependence in nanovoid-embedded high-entropy-alloy films under biaxial tension. <i>Archive of Applied Mechanics</i> , 1	2.2	0

